

RA2L1 Group

Renesas Solution Starter Kit Capacitive Touch Evaluation System User's Manual

Renesas RA Family
RA2 Series

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(Rev.5.0-1 October 2020)

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General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

How to Use This Manual

1. Purpose and Target Readers

This is a manual for users to understand the outline and hardware functions of the RA2L1 Capacitive Touch Evaluation System (RTK0EG0022S1001BJ). This manual is intended for users who use this CPU board. A basic knowledge of electric circuits, logical circuits, and MCUs is necessary in order to use this manual.

Particular attention should be paid to the precautionary notes when using the manual. These notes occur within the body of the text, at the end of each section, and in the Usage Notes section.

The revision history summarizes the locations of revisions and additions. It does not list all revisions. Refer to the text of the manual for details.

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Precautions

This Evaluation Kit is only intended for use in a laboratory environment under ambient temperature and humidity conditions. A safe separation distance should be used between this and any sensitive equipment. Its use outside the laboratory, classroom, study area, or similar such area invalidates conformity with the protection requirements of the Electromagnetic Compatibility Directive and could lead to prosecution.

The product generates, uses, and can radiate radio frequency energy and may cause harmful interference to radio communications. There is no guarantee that interference will not occur in a particular installation. If this equipment causes harmful interference to radio or television reception, which can be determined by turning the equipment off or on, you are encouraged to try to correct the interference by one or more of the following measures:

- Ensure attached cables do not lie across the equipment.
- Reorient the receiving antenna.
- Increase the distance between the equipment and the receiver.
- Connect the equipment into an outlet on a circuit different from that which the receiver is connected.
- Power down the equipment when not in use.
- Consult the dealer or an experienced radio/TV technician for help.

Note: It is recommended that wherever possible shielded interface cables are used.

The product is potentially susceptible to certain EMC phenomena. To mitigate against them it is recommended that the following measures be undertaken:

- The user is advised that mobile phones should not be used within 10 m of the product when in use.
- The user is advised to take ESD precautions when handling the equipment.

The Evaluation Kit does not represent an ideal reference design for an end product and does not fulfill the regulatory standards for an end product.

Safety Items

Definitions of Symbols

A variety of symbols are used in this document and on the product itself to prevent in advance danger to you the user or any third parties and to prevent in advance damage to any physical property.

This section, Safety Items, presents these symbols and their meanings. It also presents safety notes to assure that this produce is used safely and correctly.

This product should only be used after fully understanding the material presented in this section.



Warning

Warning items indicate things that, if not avoided, could lead to death or serious injury.



Caution

Caution items indicate both latent dangers that can lead to minor or moderately severe injury and latent dangers that can lead to property damage if not avoided.

In addition to the above two markings, the following are displayed at the same time if appropriate.

[Important] Indicates a point that can lead to equipment failure or malfunction if incorrectly set when setting up this product.

A triangular mark \triangle indicates a warning or caution.

Example:



Electrical Shock Hazard

The



mark indicates something that is forbidden.

Example: :



Do Not Disassemble

Warning



Warning

Handling related warnings:



Do not disassemble or modify this product. Renesas does not guarantee this product if it has been disassembled or modified.

The power supply for this product can be selected to be either the USB bus or a DC jack. A jumper is used to select the power supply.

If, during either use or storage of this product, any abnormality in the product itself (including abnormal odors, heating, color changes, or shape changes to the product itself) are observed, disconnect the USB cable and power supply cable immediately.

Installation:



Do not install this equipment in a location that has a high humidity or where water or other fluids could get on it. This equipment may be damaged if water or other fluids could get on it.

Ambient temperature:



The upper limit for the ambient temperature under which this product may be used is 35°C.

This maximum rated ambient temperature must not be exceeded.

Caution

Caution

Handling related cautions:

Use the antistatic band. Failure to do so could cause malfunction or unstable motion or be damaged Internal components.

This product must be handled carefully. Do not drop, knock over, or apply any strong mechanical shocks to this product.



When connecting or disconnecting cables from this product, hold the parts of the cable intended to be grasped (such as the plugs) and avoid putting stress on the cable. Do not pull on this product when it is connected to a communications cable or user system connection cable. Stress on the cable can result in internal disconnections in the cable. When connecting a cable to a connector, be careful not to insert the plug in the reverse orientation. Reverse insertion can result in damage to this product itself or to connected equipment.

The power supply for this product can be selected from two options (the DC jack or the USB cable). The jumper JP2 (on the top side of the circuit board) is used to select the power supply. Always check the jumper position before connecting a power source. An incorrect jumper position can result in damage to this product or the PC connected over the USB cable.

Do not handle this product with wet hands. This can lead to failure of the product.

Transport methods:



When transporting this product, use the product's packing box and cushioning materials and ship it with precision equipment handling. If the products packing is insufficient, it may be damaged during shipping.

If it must be transported by some other method, pack it carefully as precision equipment.

When packing this product, always use the antistatic pouch included with this product.

If some other pouch is used, damage to the product may be caused by electrostatic discharge.

Abnormal operation:



If operation of this product becomes abnormal due to interference from, for example, external noise, apply the following procedure.

1. Turn off the power.
2. Wait 10 seconds and then turn the power back on.

Disposal:



When disposing of this product, handle it as industrial waste according to all applicable laws.



European Union regulatory notices:

The WEEE (Waste Electrical and Electronic Equipment) regulations put responsibilities on producers for the collection and recycling or disposal of electrical and electronic waste. Return of WEEE under these regulations is applicable in the European Union only. This equipment (including all accessories) is not intended for household use. After use the equipment cannot be disposed of as household waste, and the WEEE must be treated, recycled and disposed of in an environmentally sound manner. Renesas Electronics Europe GmbH can take back end of life equipment, register for this service at "<http://www.renesas.eu/weee>".

Electromagnetic Environment



Electromagnetic Environment



- This product generates electromagnetic emissions in an industrial environment. Use in a residential environment may affect other equipment.
- This product requires special EMC precautions and should be used in accordance with the EMC information provided below.

EMI: Electro Magnetic Interference

Standard		Level	Guidance for EMC protection
Test Item	EN 55011 :2016/A1:2017/A2:2021	Group1 Class A	This product has no intentional external emissions, but internal RF emissions may affect nearby electromagnetically sensitive electronic equipment.
Radiated Emissions			
Conducted Emissions			

EMS: Electro Magnetic Susceptibility

Standard		Level	Guidance for EMC protection
Radio Frequency Electromagnetic Field	EN 61000-4-3: 2006/A1:2008/A2:2010	A* ¹	This product is intended for use in electromagnetic environments in industrial settings. The user of the product should pay particular attention to the following electromagnetic immunity. <ul style="list-style-type: none"> • Power supply quality • Protection against static electricity • Protection against external high-power radio waves • Protection against external magnetic fields
Electrical Fast Transient / Burst	EN 61000-4-4:2012	B* ²	
Surge	EN 61000-4-5 :2014/A1:2017	B* ³	
Conducted Disturbance, Induced by Radio Frequency	EN 61000-4-6:2014	A* ⁴	
Power Frequency Magnetic Field	EN 61000-4-8:2010	A* ⁵	
Voltage Dips and Interruptions	EN IEC 61000-4-11:2020	B or C* ⁶	

*1 Test Condition of Radio Frequency Electromagnetic Field

Test Level	Dwell Time	Modulation	Frequency Step	Antenna Polarization	Result
3V/m (80MHz - 1.0GHz)	1.0sec	1kHz AM 80%	1.0%	Horizontal / Vertical	Pass
3V/m (1.4GHz – 6.0GHz)					Pass

*2 Test Condition of Electrical Fast Transient / Burst

Test Level	Wave Form	Repetition Frequency	Testing Duration	Result
±1.0kV	Rise time: 5.0nsec Pulse Duration: 50nsec	5kHz	60sec	Pass
		100kHz		Pass

*3 Test Condition of Surge

Test Level	Wave form Specification	Phase Angle	Result
±0.5kV	Front time: 1.2 / 8.0 µsec Time to half value: 50 / 20 µsec	0°, 90°, 180°, 270°	Pass
			Pass

*4 Test condition of Conducted Disturbance, Induced by Radio Frequency

Test Level	Dwell Time	Modulation	Frequency Step	Result
3V (0.15MHz – 80MHz)	1.0 sec	1kHz AM 80%	1.0%	Pass

*5 Test Condition of Power Frequency Magnetic Field

Test Level	Applied Power Frequency	Test Duration	Result
3A/m (rms)	50Hz	60sec	Pass
	60Hz		Pass

*6 Test Condition of Voltage Dips and Interruptions

Test Item	Test Level	Duration	Phase Angle	Result
Voltage Dips	0%	0.5 cycles	0°, 180°	Pass
		1.0 cycles		Pass
	70%	25 cycles		Pass
Voltage Interruptions	0%	250 cycles		Pass

Renesas RA Family

RA2L1 Group Capacitive Touch Evaluation System User's Manual

Contents

1. Overview	3
2. Product Configuration	4
3. Product Ordering Information.....	5
4. Hardware Details	6
4.1 Jumper Settings.....	6
4.1.1 Default Board Settings	6
5. Board Layout	6
5.1 Block Diagram	6
5.2 Power Supply	7
5.2.1 Power Supply Options.....	7
5.2.1.1 USB MicroB connector (default setting).....	7
5.2.1.2 DC jack.....	7
5.2.1.3 Power source ON operations	7
5.2.1.4 Current measurement	8
5.3 Connectivity	8
5.3.1 USB Serial Conversion.....	8
5.3.2 Debug Interface	8
5.3.3 LEDs.....	8
5.3.4 Switches	8
5.3.5 Application Board Interface	9
5.4 Added Functions.....	10
5.4.1 Clock Circuit	10
5.4.2 MCU Operating Mode Settings	10
5.4.3 Internal Voltage Regulator Circuit	11
5.4.4 CTSU Related Circuits	11
5.4.4.1 CTSU correction circuit	11
6. Capacitive Touch Application Board	12
6.1 CPU Board Connection	12
6.2 Signal Assignments.....	13
7. Certifications.....	14
7.1 European Union regulatory notices	14
8. Website and Support	15
Revision History.....	16

Figures

Figure 1. RA2L1 Cap Touch CPU Board Top Side	4
Figure 2. Application Board Top Side	5
Figure 3. RA2L1 Cap Touch CPU Board Block Diagram	6
Figure 4. Power Source System Diagram	7
Figure 5. RA2L1 Operating Mode Setting Circuit	10
Figure 6. Internal Voltage Regulator Circuit	11
Figure 7. RA2L1 Cap Touch CPU Board and Capacitive Touch Application Board Connection Method.....	12

Tables

Table 1. Default Board Settings	6
Table 2. Power Source Jumper Settings	7
Table 3. MCU Connections for USB Serial Conversion	8
Table 4. LED Functions	8
Table 5. Push Switch Specifications.....	8
Table 6. Application Board Connector (CN1)	9
Table 7. Application Board Connector (CN2)	9
Table 8. Clock Specifications	10
Table 9. RA2L1 Operating Mode Settings.....	10
Table 10. Jumpers for Programming in SCI Boot Mode.....	10
Table 11. CTSU Correction Circuit Settings	11
Table 12. Application Header (CN1).....	13
Table 13. Application Header (CN2).....	13

1. Overview

The RA2L1 MCU Group Capacitive Touch Evaluation System (RTK0EG0022S01001BJ) is a kit created for evaluating the RA2L1 MCU Group Capacitive Touch Sensing Unit (CTSUS).

RTK0EG0022S01001BJ is composed of two boards: The RA2L1 Cap Touch CPU Board is mounted with an RA2L1 MCU which includes an on-chip CTSU. The Capacitive Touch Application Board Capacitive Touch Application Board is equipped with self-capacitance touch buttons, wheel and slider electrodes, and LEDs touch electrodes.

Note: The function name of the capacitive touch sensor in RA2L1 MCU Group products is "CTSUS2," but is referred to as "CTSUS" in this document.

The main functions of the RA2L1 Cap Touch CPU board are as follows:

- Renesas RA2L1 MCU Group
 - R7FA2L1AB2DFP
 - 100-pin LFQFP package
 - 48MHz Arm Cortex®-M23 Core with built-in Arm® MPU (Armv8-M architecture)
 - 32KB SRAM
 - 256KB code flash memory
 - 8KB data flash memory
 - 32-channel capacitive touch sensing unit (CTSUS) pins
- Connectivity
 - USB serial conversion interface (FT234XD manufactured by FTDI)
 - 10-pin JTAG/SWD interface for connecting external debugger or programmer (option)
 - Application board GPIO interface: 2.54mm pitch, 16 pins (8 x 2 DIL)
 - Application board CTSUS interface: 2.54mm pitch, 40 pins (20 x 2 DIL)
- Multi-clock source
 - Main clock: 12MHz crystal oscillator (option)
 - Sub clock: 32.768KHz crystal oscillator (option)
 - On-chip oscillator for main MCU
- MCU RESET push button switch
 - MCU operating mode setting DIP switch
 - MCU boot mode setting
 - Debug interface switch setting
- Operation voltage
 - 3.3V to 5.0V
 - Power source connector (5.5 x 2.1mm center plus DC jack): 3.3V to 5.0V
 - USB bus power: 5V
- Other functions
 - MCU current measurement jumper
 - User push button switches: 2
 - User LEDs: 2

Key functions of the Capacitive Touch Application Board are as follows:

- Self-capacitance detection touch electrodes
 - Buttons: 3
 - Wheel (4-electrode configuration): 1
 - Slider (5-electrode configuration): 1
- LEDs: 16
- Renesas MCU Cap Touch CPU Board interfaces:
 - GPIO connector header: 2.54mm pitch, 16 pins (8 x 2 DIL)
 - CTSU connector header: 2.54mm pitch, 40 pins (20 x 2 DIL)
- Overlay panel
 - 2mm-thick acrylic panel

2. Product Configuration

This kit includes the following parts:

1. RA2L1 Cap Touch CPU Board (RTK0EG0018C01001BJ): 1 board
2. Capacitive Touch Application Board (RTK0EG0019B01002BJ): 1 board

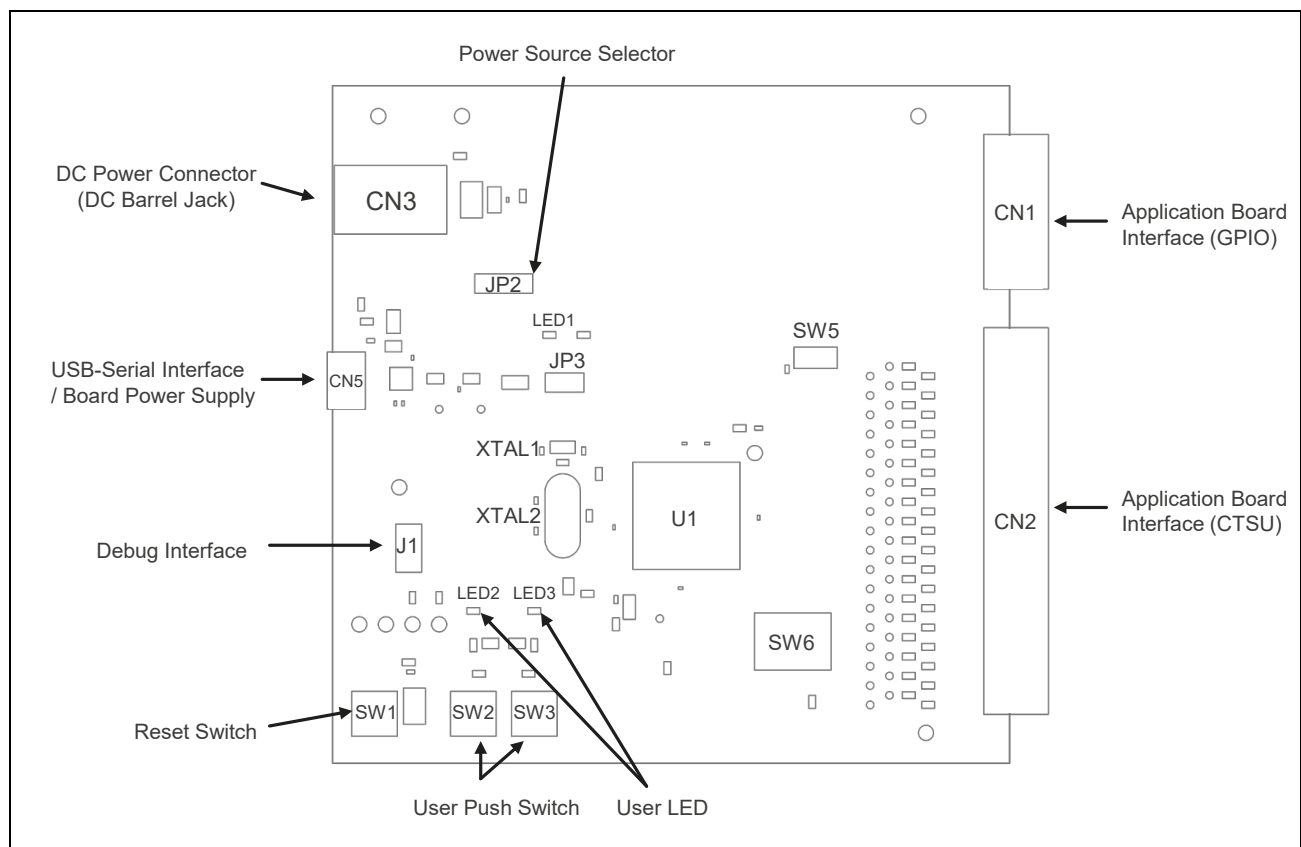


Figure 1. RA2L1 Cap Touch CPU Board Top Side

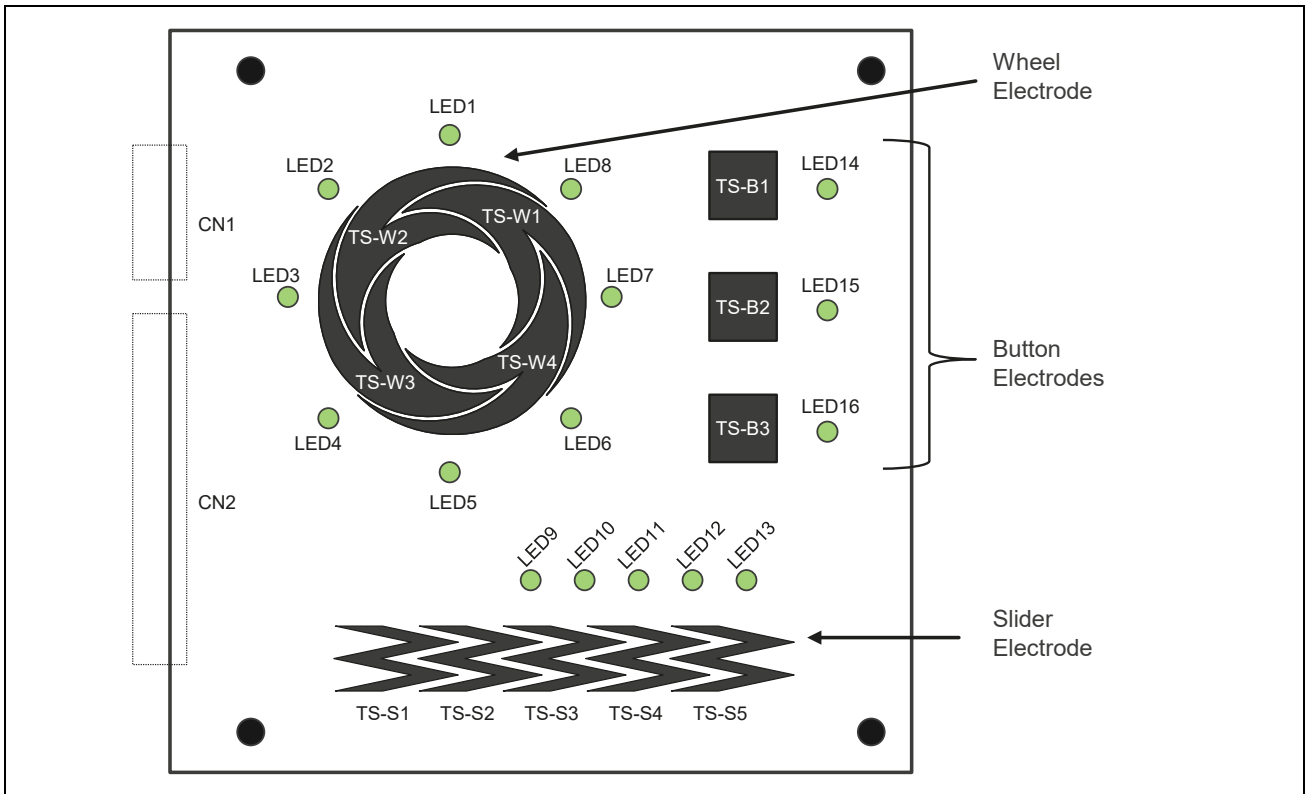


Figure 2. Application Board Top Side

3. Product Ordering Information

Part number for ordering the RA2L1 MCU Group Capacitive Touch Evaluation System:
 RTK0EG0022S01001BJ

Note: The character underlined in the part number indicates the kit version.

- RA2L1 Cap Touch CPU Board dimensions: 89 mm (W) x 89 mm (L)
- Application Board dimensions: 110 mm (W) x 110 mm (L)

4. Hardware Details

4.1 Jumper Settings

4.1.1 Default Board Settings

The following table indicates the default settings for each jumper on the RA2L1 Cap Touch CPU Board. The list includes pin jumpers (JPx), resistance jumpers (Rx), and slide switches (SWx).

For a detailed description of most jumper functions, please refer to sections 5.3 Connectivity and 5.4 Added Functions.

Table 1. Default Board Settings

Position	Circuit Group	Default State Open/Closed ON/OFF	Function
JP2	Power source	Pins 2-3 closed	Connects USB power source to board power source
JP3		Closed	Connects board power source to MCU VCC
R9	MCU internal voltage regulator	Closed	Connects VCL pin to L3
R11		Open	Connects VSS_DCDC pin to VSS pin
SW5	Capacitance touch	OFF (on the white line side)	Enables/disables CTSU correction function
SW6	MCU mode setting	1: OFF 2: OFF 3: OFF	1: Selects MCU boot mode 2: Use P109 as TS10 pin 3: Use P110 as TS11 pin
R20		Open	Connects P109 / TXD9 to test pin (TXD)
R21		Open	Connects P110 / RXD9 to test pin (RXD)

5. Board Layout

5.1 Block Diagram

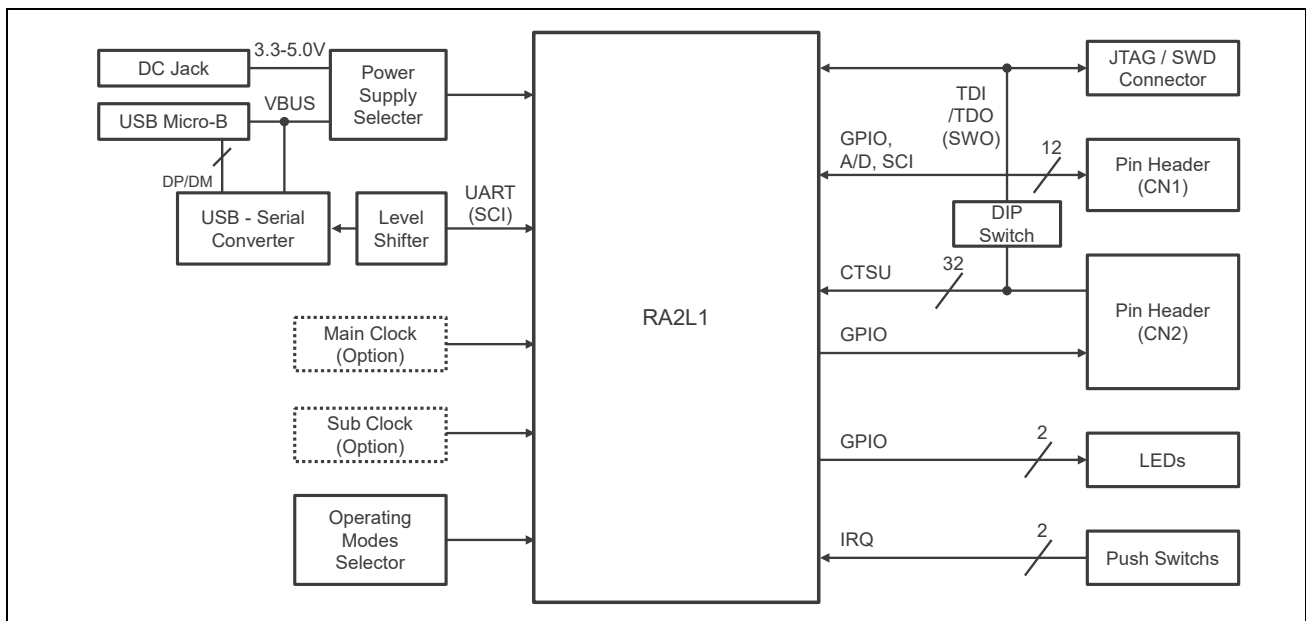


Figure 3. RA2L1 Cap Touch CPU Board Block Diagram

5.2 Power Supply

The RA2L1 Cap Touch CPU Board is designed to run on 3.3 to 5.0V.

5.2.1 Power Supply Options

This section explains several methods for supplying power to the RA2L1 Cap Touch CPU Board.

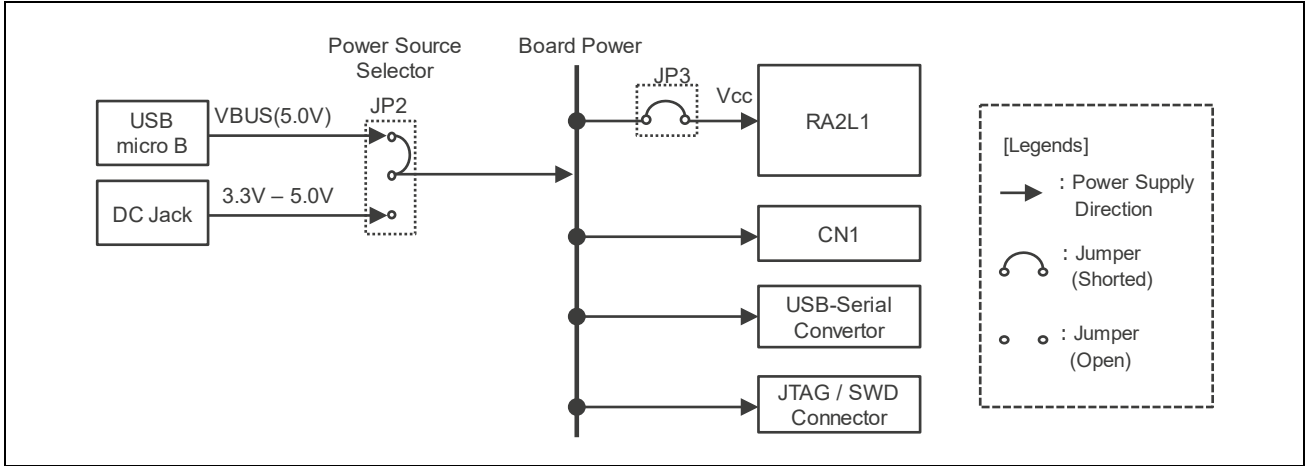


Figure 4. Power Source System Diagram

Table 2. Power Source Jumper Settings

Reference	Jumper Setting	Default Setting (X)	Description
JP2	Shorted Pins 1-2		Connects DC jack (CN3) to board power source
	Shorted Pins 2-3	X	Connects USB power source to board power source
JP3	Shorted Pins 1-2	X	Connects board power source to the MCU's VCC.
	All open		MCU current consumption measurement setting

5.2.1.1 USB MicroB connector (default setting)

By default, 5V external power is supplied to the MCU and connected devices via the USB MicroB connector.

5.2.1.2 DC jack

Board power also can be supplied by connecting a power source to the DC jack. To power the board via the DC jack, shorten pins 2-3 in the JP2 short block.

5.2.1.3 Power source ON operations

LED1 (red) lights up when the power is turned on.

5.2.1.4 Current measurement

The MCU's supply current can be measured using jumper pin JP3. To do so, remove the short block from JP3 and connect an ammeter.

The actual current consumed by the RA2L1 MCU varies based on ambient temperature, internal clock speed, input voltage level, device operating state, and many other factors. Actual MCU current consumption ranges from less than 1mA to nearly 40mA. For detailed electrical characteristics, refer to the *RA2L1 MCU Group User's Manual*.

5.3 Connectivity

5.3.1 USB Serial Conversion

The RA2L1 Cap Touch CPU Board is equipped with USB serial IC FT234XD (FTDI Ltd.) for USB serial conversion. The FT234XD is connected to the RA2L1's serial communication interface (SCI) module. When using this function, use the shortest possible USB cable.

Table 3. MCU Connections for USB Serial Conversion

Signal Name	MCU Control Port	Function
TXD	P203 / TXD9_A	SCI9 transmit data signal
RXD	P202 / RXD9_A	SCI9 receive data signal

5.3.2 Debug Interface

Connector J1 mounted on the RA2L1 Cap Touch CPU Board is a 10-pin Cortex® debug connector interface.

Note: The RA2L1 MCU does not support JTAG; it only supports SWD.

For details on the Cortex® debug connector, refer to the Arm® CoreSight™ Architecture Specification.

5.3.3 LEDs

The RA2L1 Cap Touch CPU Board is equipped with 3 LEDs. LED operations are described in the following table.

Table 4. LED Functions

Reference	Color	Function	MCU Control Port
LED1 (Power)	Red	Power status display	VCC
LED2	Green	User LED	P305
LED3	Yellow	User LED	P304

5.3.4 Switches

The RA2L1 Cap Touch CPU Board is equipped with 3 push-button type SMT momentary switches, as described in the following table. Pressing the RESET switch will generate a reset signal to restart the main MCU.

Table 5. Push Switch Specifications

Reference	Function	MCU Control Port
SW1 (RESET)	Resets the MCU.	RES
SW2	User controllable switch	P206 / IRQ0
SW3	User controllable switch	P205 / IRQ1

5.3.5 Application Board Interface

Connectors CN1 and CN2 on the application board are provided as interfaces for connection to the user board.

CN1 is for GPIO pins. For unlisted peripheral functions, refer to the *RA2L1 MCU Group User's Manual*.

CN2 is mostly used for CTSU pins. Although GPIOs can also be connected, CN2 should be fixed to low by software for normal use. Do not connect anything to TSCAP.

Table 6. Application Board Connector (CN1)

CN1			MCU			CN1			MCU		
Pin	Port	Peripheral	Pin	Port	Peripheral	Pin	Port	Peripheral	Pin	Port	Peripheral
16	VSS (GND)	VSS	15	VCC	VCC						
14	P006	AN012	13	P414	—						
12	P415	—	11	P708	—						
10	P401	IRQ5	9	P404	—						
8	P405	—	7	P406	—						
6	P714	—	5	P400	—						
4	P504	SS1_C	3	P502	MISO1_C						
2	P503	SCK1_C	1	P501	MOSI1_C						

— : Not Applicable

Table 7. Application Board Connector (CN2)

CN2			MCU			CN2			MCU		
Pin	Port	CTSU	Pin	Port	CTSU	Pin	Port	CTSU	Pin	Port	CTSU
40	P112	TSCAP	39	—	—						
38	—	—	37	—	—						
36	P402	TS18	35	P403	TS17						
34	P000	TS21	33	P001	TS22						
32	P003	TS24	31	P002	TS23						
30	P010	TS30-CFC	29	P004	TS25						
28	P012	TS32-CFC	27	P011	TS31-CFC						
26	P015	TS28-CFC	25	P013	TS33-CFC						
24	P101	TS16-CFC	23	P100	TS26-CFC						
22	P103	TS14-CFC	21	P102	TS15-CFC						
20	P105	TS34-CFC	19	P104	TS13-CFC						
18	P107	—	17	P107	—						
16	P107	—	15	P107	—						
14	P114	TS29-CFC	13	P115	TS35-CFC						
12	P111	TS12-CFC	11	P113	TS27-CFC						
10	P109	TS10-CFC	9	P110	TS11-CFC						
8	P301	TS09-CFC	7	P204	TS00						
6	P302	TS08-CFC	5	P408	TS04						
4	P303	TS02-CFC	3	P409	TS05						
2	P411	TS07	1	P410	TS06						

— : Not Applicable

5.4 Added Functions

5.4.1 Clock Circuit

The RA2L1 Cap Touch CPU Board comes with 2 high-precision crystal clock sources.

Table 8.Clock Specifications

Clock	Function	Frequency	Default State	Package
X1	Sub clock	32.768kHz	Not mounted	HC-49
X2	Main clock	12MHz	Not mounted	3.2mm x 1.5mm SMD

5.4.2 MCU Operating Mode Settings

DIP switch SW6 is used to set the RA2S1 operating mode.

Table 9. RA2L1 Operating Mode Settings

Reference	Channel	Position	Default Setting (X)	Setting
SW6	1	OFF	X	MCU operates in "Single Chip Mode"
		ON		MCU operates in "SCI Boot Mode"
	2	OFF	X	Use P109 as TS10 pin
		ON		Use P109 as TDO/SWO pin
	3	OFF	X	Use P110 as TS11 pin
		ON		Use P110 as TDI pin

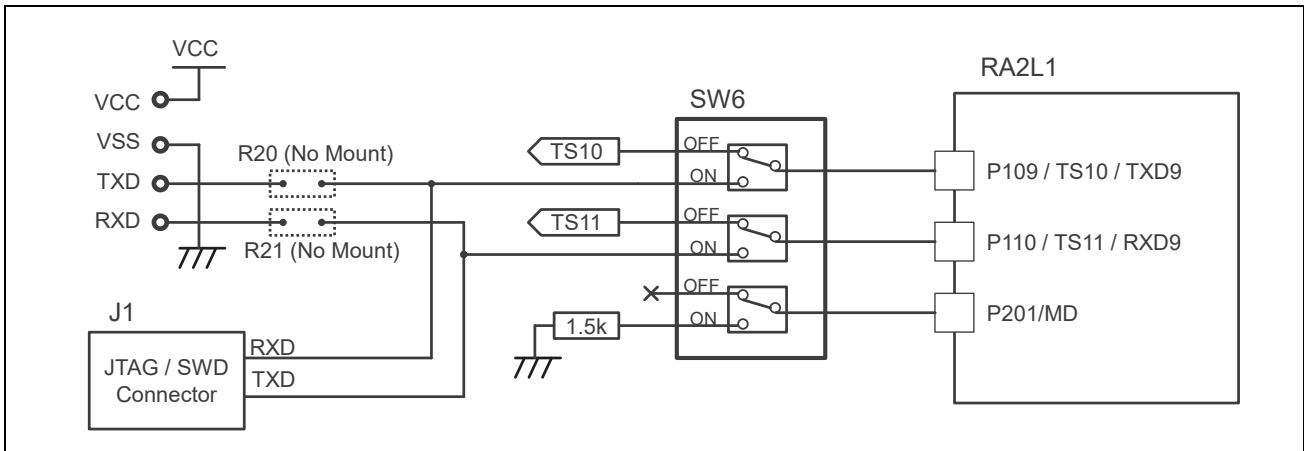


Figure 5. RA2L1 Operating Mode Setting Circuit

When starting up the MCU in SCI Boot Mode for onboard programming, short the SCI Boot Mode programming jumpers listed in the following table. Make sure you do not connect the debugger when programming onboard in the SCI Boot Mode.

Table 10. Jumpers for Programming in SCI Boot Mode

Reference	Function	Default State	Spec.	Package
R20	Connects P109 / TXD9 to test pin (TXD)	Not mounted	0 Ohm	1.6mm x 0.8mm SMD
R21	Connects P110 / RXD9 to test pin (RXD)	Not mounted	0 Ohm	1.6mm x 0.8mm SMD

5.4.3 Internal Voltage Regulator Circuit

The RA2L1's internal voltage regulator can be set by software to be used in the LDO mode (default) or DCDC mode. To use the regulator in the DCDC mode, short the R11 pin.

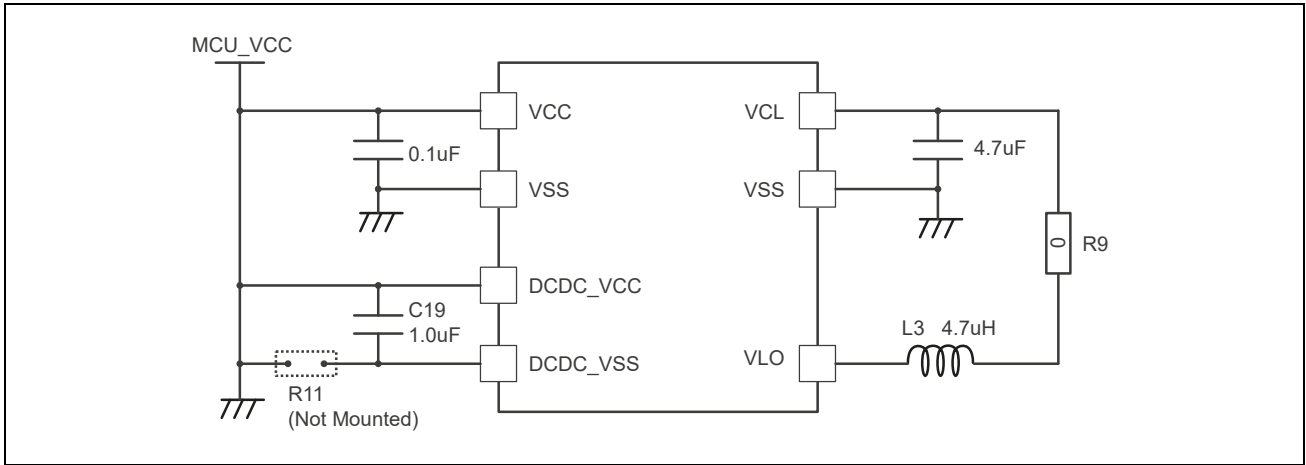


Figure 6. Internal Voltage Regulator Circuit

5.4.4 CTSU Related Circuits

5.4.4.1 CTSU correction circuit

This circuit improves the absolute accuracy of the CTSU's capacitive measurement. This function requires the use of additional control software (sold separately). When using the CTSU pin in normal conditions make sure you it set to the OFF position.

Table 11. CTSU Correction Circuit Settings

Reference	Position	Default Setting (X)	Setting
SW5	OFF	X	Use TS21 as the normal CTSU pin
	ON		Use TS21 as the CTSU correction pin

6. Capacitive Touch Application Board

The Capacitive Touch Application Board is equipped with self-capacitance touch buttons, wheel and slider touch electrodes, and multiple LEDs.

6.1 CPU Board Connection

The two boards can be connected using the application header (CN1 and CN2) connectors on the Capacitive Touch Application Board and the application board connectors (CN1 and CN2) on the RA2L1 Cap Touch CPU Board.

Ensure that all CN1 and CN2 pins of both boards are connected correctly by inserting as indicated by the arrows in the following figure.

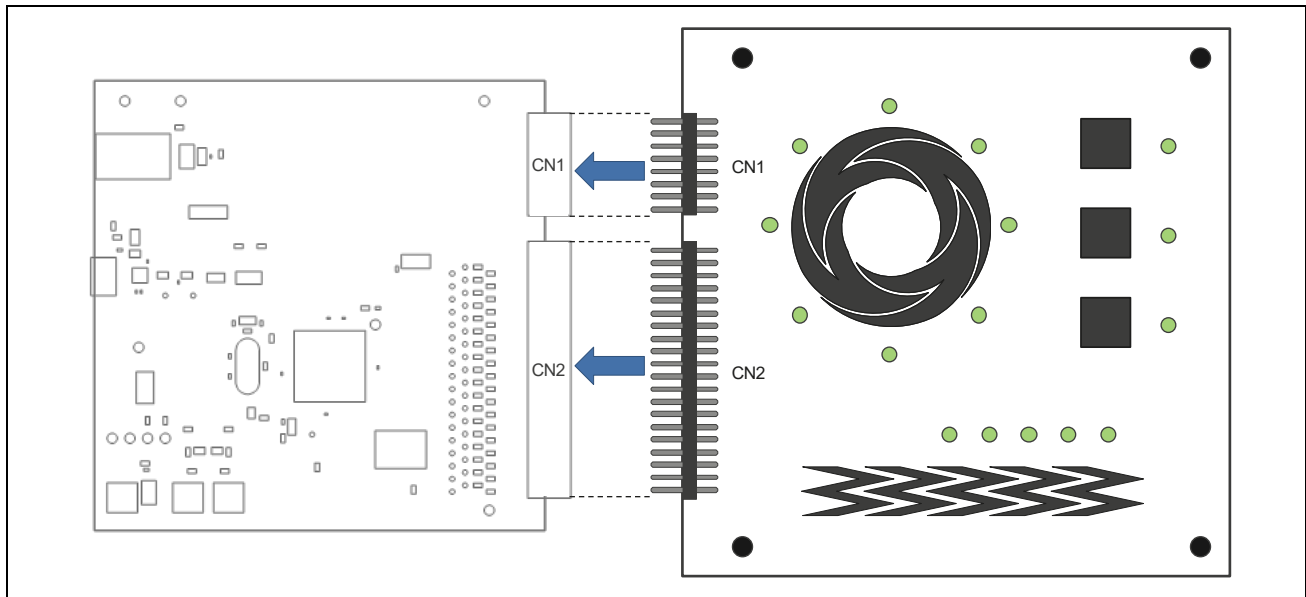


Figure 7. RA2L1 Cap Touch CPU Board and Capacitive Touch Application Board Connection Method

6.2 Signal Assignments

Application headers CN1 and CN2 on the Capacitive Touch Application Board are interfaces for connections to the Renesas Capacitive Touch Evaluation System's CPU board and to the GPIO and CTSU ports. The following table lists the signal assignments between the Capacitive Touch Application Board and RA2L1 Cap Touch CPU Board.

Table 12. Application Header (CN1)

CN1 Pin	Function	MCU Connection	CN1 Pin	Function	MCU Connection
15	VCC	VCC	16	VSS (GND)	VSS
13	LED_ROW0	P414	14	LED_ROW1	P006
11	LED_ROW2	P708	12	LED_ROW3	P415
9	—	P404	10	—	P401
7	LED_COL3	P406	8	—	P405
5	LED_COL1	P400	6	LED_COL2	P714
3	—	P502	4	LED_COL0	P504
1	—	P501	2	—	P503

— : Not Applicable

Table 13. Application Header (CN2)

CN2 Pin	Touch Electrode	CTSU (RA2L1)	CN2 Pin	Touch Electrode	CTSU (RA2L1)
39	—	—	40	—	TSCAP
37	—	—	38	—	—
35	—	TS17	36	TS-W1	TS18
33	—	TS22	34	TS-W2	TS21
31	TS-W3	TS23	32	—	TS24
29	—	TS25	30	—	TS30-CFC
27	—	TS31-CFC	28	TS-W4	TS32-CFC
25	—	TS33-CFC	26	—	TS28-CFC
23	—	TS26-CFC	24	—	TS16-CFC
21	—	TS15-CFC	22	SHIELD-W1	TS14-CFC
19	—	TS13-CFC	20	—	TS34-CFC
17	—	—	18	—	—
15	—	—	16	—	—
13	—	TS35-CFC	14	—	TS29-CFC
11	—	TS27-CFC	12	—	TS12-CFC
9	TS-B1	TS11-CFC	10	TS-B2	TS10-CFC
7	SHIELD-B1	TS00	8	TS-B3	TS09-CFC
5	TS-S1	TS04	6	SHIELD-S1	TS08-CFC
3	TS-S3	TS05	4	TS-S2	TS02-CFC
1	TS-S5	TS06	2	TS-S4	TS07

— : Not Applicable

Note : SHIELD-S1、SHIELD-W1 and SHIELD-B1 are shield electrodes. To enable the function, set the pin to shield signal output mode by software.

7. Certifications

7.1 European Union regulatory notices

This product complies with the following EU Directives. (These directives are only valid in the European Union.)

CE Certifications:

- Electromagnetic Compatibility (EMC) Directive 2014/30/EU
EN IEC 61326-1: 2021 Group1 Class A

WARNING: This is a Class A product. This equipment can cause radio frequency noise when used in the residential area. In such cases, the user/operator of the equipment may be required to take appropriate countermeasures under his responsibility.

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 - Trademark and Type name
Trademark: Renesas
Product name: RA2L1 Capacitive Touch Evaluation System
Type name: RTK0EG0022S01001BJ

Environmental Compliance and Certifications:

Waste Electrical and Electronic Equipment (WEEE) Directive 2012/19/EU

8. Website and Support

Visit the following URLs to learn about the kit and the RA family of microcontrollers, download tools and documentation, and get support.

- RTK0EG0022S01001BJ Resources renesas.com/rssk-touch-ra2l1
- Renesas Capacitive Touch Sensor Solutions renesas.com/solutions/touch-key
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Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Jun.03.20	-	First edition issued
1.10	Dec.26.23	- 14	Additions and changes due to updated EMC standard. <ul style="list-style-type: none">• How to Use This ManualAdded description of electromagnetic environment• 7. CertificationsEN61326-1: 2013 → EN IEC 61326-1: 2021
1.11	Nov.19.25	6	Deleted a link error message in Japanese

RA2L1 Group Renesas Solution Starter Kit
Capacitive Touch Evaluation System User's Manual

Publication Date: Rev.1.00 Jun.3.20
Rev.1.10 Dec.26.23
Rev.1.11 Nov.19.25

Published by: Renesas Electronics Corporation

Renesas RA2L1 Group
Renesas Solution Starter Kit
Capacitive Touch Evaluation System
User's Manual

